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SERIAL NO. 09/222,524

APPLICANT(S)
MATSUDA

FILING DATE
DECEMBER 28, 1998

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U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

22		Matuda S. et al "SIMPLE-STRUCTURE, GENERALLY APPLICABLE CHIP-SCALE PACKAGE" Proceedings of the electronic components and technology conference, US, New York, IEEE, Vol. Conf. 45, 1995, pages 218-223, XP000624972, ISBN: 0-7803-2737-3
22		Matsuda S. et al "DEVELOPMENT OF CHIP SCALE PACKAGE (CSP) USING THROUGH-HOLE BONDING AND TRANSFER MOLDING PROCESS" NEC Research and Development, JP, Nippon Electric LTD. Tokyo, Vol. 38, No. 3, July 1, 1997, pages 318-325, XP000742627, ISSN: 0547-051X

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DATE CONSIDERED

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"IMPROVED METHOD FOR C-4 CHIP JOIN" IBM Technical Disclosure Bulletin, US, IBM Corp. New York, Vol. 31, No. 6, November 1, 1988, pages 335-336, XP000054208, ISSN: 0018-8689

EXAMINER

Nitin Pareek

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